



S3A2U3-A2

2U & 3U PCI Express x16 Gen 3.0 Host Connector to Two TWINAX Connectors Interface Adapter

Product Description

The Silicom SETAC is a solution that converts a standard server to a network appliance.

- Front system I/O ports
- I/O modules can be replaced without opening the server chassis
- Higher ports density than a standard server
- More reliable solution than a standard PCI Express NIC

SETAC Network appliances are based on standard server with front hot-swap HD.

The SETAC Network appliance includes SETAC backplane that replaces a server HD backplane.

In a standard server, a HD backplane supports only SAS / SATA technology – Silicom SETAC backplane supports PCI Express and SAS / SATA technology.

Silicom SETAC solution based on Silicom ExpressModule cards, providing widest networking and Bypass solution. The Silicom' s S3A2U3-A2 is Express x16 Gen 3.0 Host Connector to Two TWINAX Connectors Interface Adapter

Key Features

Performance Features:

- Based on server grade reliability
- Leverage the price / performance / reliability of standard server
- Maximize the I/O ports and interfaces
- Field replaceable – End user can change the configuration without opening of sever chassis
- High quantity of various configurations can be efficiently handled and final configuration can be done just before shipment
- Server and IO module flexibility:
 - Based on standard server
 - Based on Silicom ExpressModule cards
- Simpler maintenance – Components can be replaced quickly and assuredly



Reliable solution:

- Based on current SATA backplane
- Better than SATA cables
- Better than standard add-in PCI form factor
- Based on embedded solutions –Up to 5 years product life cycle

Host Interface:

- Host Interface standard support PCI Express 3.0 (8Gb/s)
- PCI Express X16 lanes
- Signaling and interface based on PCI-Express EM standard (PCI-SIG) ver. 3.0 (8.0 GT/s)
- PCI-E EM Backplane replacing HD Backplane
- PCI Express ExpressModule Electromechanical Specification Revision 1.0 (2.0)
- PCI Express External Cabling Specification Revision 1.0 (2.0)
- PCI Express External Cabling Specification 2.0 Revision 0.3 RC2

Technical Specifications

General Technical Specifications	
Size:	6.6"x 2.535" (167.64mm x 64.389mm)
PCI Express Card Type:	X16 Lane
Voltage:	+12V (Min 11.04V, Max, 12.96V)
Holder:	Metal Bracket
Weight:	90gr (3.175 oz)
Power Consumption:	3W, 0.25A at 12V: Typical Idle 9.12W, 0.76A at 12V: Typical one slot 9.6W, 0.8A at 12V: Typical two slot
Operating Humidity:	0%–90%, non-condensing
Operating Temperature:	0°C – 50°C (32°F – 122°F)
Storage Temperature:	-20°C–65°C (-4°F–149°F)
EMC Certifications:	Class B

MTBF*:	177(Years) *According to Telcordia SR-332 Issue 1 Environmental condition – GB (Ground, Fixed, Controlled). Ambient temperature – 25°C. Temperature rise of 15°C above the system ambient temperature was assumed for the cards components
Connector Specifications	
Connectors:	(2) iPass Connector

Order Information

P/N	Description	Notes
S3A2U3-A2	2U PCI Express Gen 3.0 x16 Host Connector to Two TWINAX Connectors Interface Adapter (with power to backplane)	PCI Express Gen 3.0 x16 Host Connector Assembled with Low Profile Metal Bracket
S3A3U3-A2	3U PCI Express Gen 3.0 x16 Host Connector to Two TWINAX Connectors Interface Adapter (with power to backplane)	PCI Express Gen 3.0 x16 Host Connector Assembled with full height Metal Bracket

Model P/N -LP /

-LP: Assemble Low Profile Metal Bracket

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